

0905028099

*AUTO EQUIPMENT*  
**SOLUTION PROVIDER**

萬潤科技

**AllRing Tech**

**Stock Code:6187.TT**



# Disclaimer

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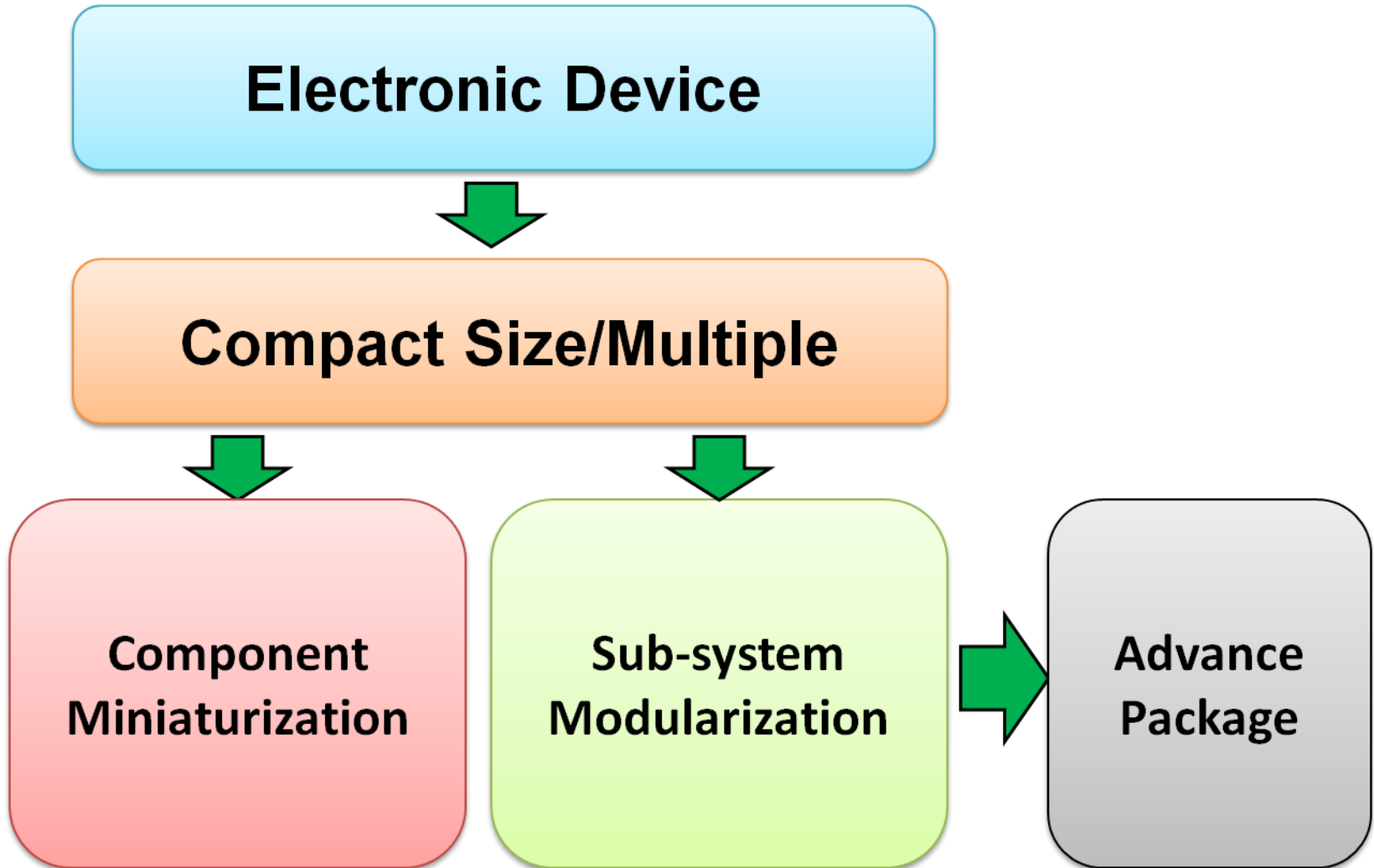


- 1 **Company Profile**
- 2 Industry Overview
- 3 Financial Highlights
- 4 Future Prospects

# Company Profile

|                    |  |
|--------------------|--|
| <b>Established</b> | May 24, 1996   |
| <b>Capital</b>     | NTD 833 Million (USD 27 Million)   |
| <b>Business</b>    | Automation equipment supplier for Semiconductor test & package, Passive Component manufacturing industries |
| <b>Employee</b>    | 219 (Feb, 2020)  |
| <b>Chairman</b>    | Larry Lu   |
| <b>Address</b>     | No.1 Luke 10th Rd. ,Lujhu,Kaohsiung,Taiwan   |
| <b>Website</b>     | <a href="http://www.allring-tech.com.tw">www.allring-tech.com.tw</a>                                       |












# Industry Overview



# Advance Package

| Packaging Type               |       | Manufacturer |                     | Application                  |
|------------------------------|-------|--------------|---------------------|------------------------------|
| SIP<br>(system in package)   |       | OSAT         | ASE                 | Smart phone<br>IoT<br>Mobile |
|                              |       |              | USI                 |                              |
|                              |       | Module house | Hon Hai<br>Pegatron |                              |
|                              |       |              | Component           |                              |
| WLP<br>(wafer level package) | InFO  | Foundry      | TSMC                | Smart Phone                  |
|                              | CoWoS |              | TSMC                |                              |
| Flip chip                    | 2D/3D | OSAT         | ASE                 | Smart Phone<br>IoT<br>Mobile |
|                              |       |              | Spil                |                              |
|                              |       |              | Amkor               |                              |
|                              |       |              | JCET                |                              |
|                              |       |              | Powertech           |                              |

# Customer Base

| Semiconductor   | Passive Component   |
|---|---|
|         |              |

# Product line up

## Mounter Series of Semiconductor



- ◆ Optical Adhesion Attach
- ◆ PSA Attach
- ◆ FPC Mounter
- ◆ ACF Mounter

### Why us?

- ✓ Customized Design for different size and shape products.
- ✓ Included In-House AOI and sensing control




# Product line up

## Dispenser Series

- ◆ Under Fill Dispenser (BGA/Wafer)
- ◆ Flux Jetting Dispenser
- ◆ Heat Sink Dispenser

### In-House Pump type

- ◆ Jetting
- ◆ Auger
- ◆ Spray
- ◆ Air pulse

| Type                                     | Jetting   |
|--|---|
|  | RK-PIEZO 3000   |
|  |  |
| Dispensing Method                        | Piezo-electric  |
| Fluid Viscosity range, mPa.s (reference) | 10 ~ 80,000   |
| Operation Cycle, dps                     | Max. 1000   |
| Dot Weight, mg/dot                       | 0.002~0.1   |
| Dispensing Precision                     | 1mg±5%<br>$C_{PK} > 1.66$   |



# Product line up

## AOI Series of Semiconductor



- ◆ Die Bonding AOI
- ◆ 6 surface Inspection
- ◆ Wafer UF Inspection

# Product line up

## Auto Machine Series of Semiconductor

- ◆ Loader & Unloader
- ◆ Carrier Conversion Machine
- ◆ Integrated System

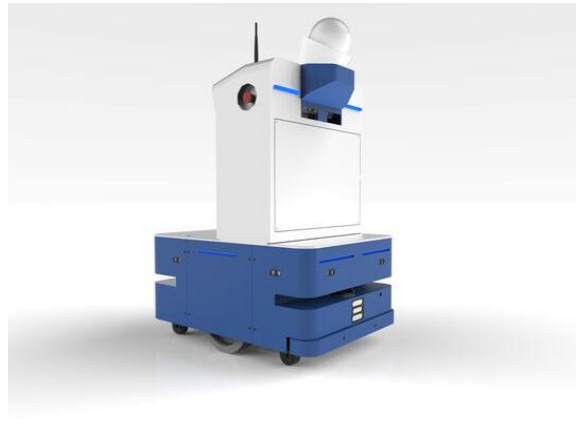


# Product line up

## Auto Machine Series



MOBILE ROBOT



SECURITY ROBOT



CLEANING ROBOT

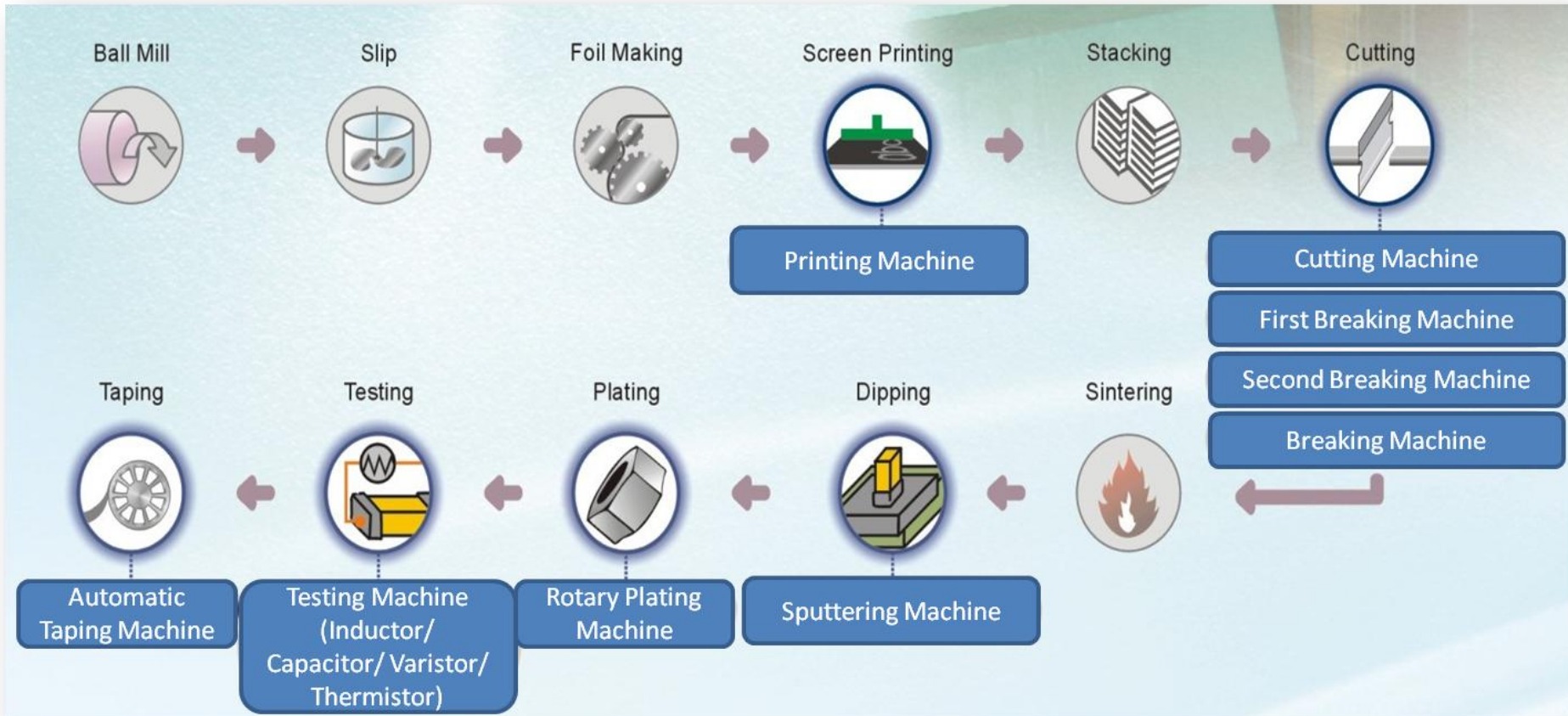
# Product line up

## Passive Component



- ◆ Rotary Plating Machine
- ◆ R-Chip Taping Machine
- ◆ Cutting Machine
- ◆ Chip Resistor Breaking Machine
- ◆ MLCI(High Frequency) Taping Machine (0.4\*0.2mm chip)

# Passive Component Production Process

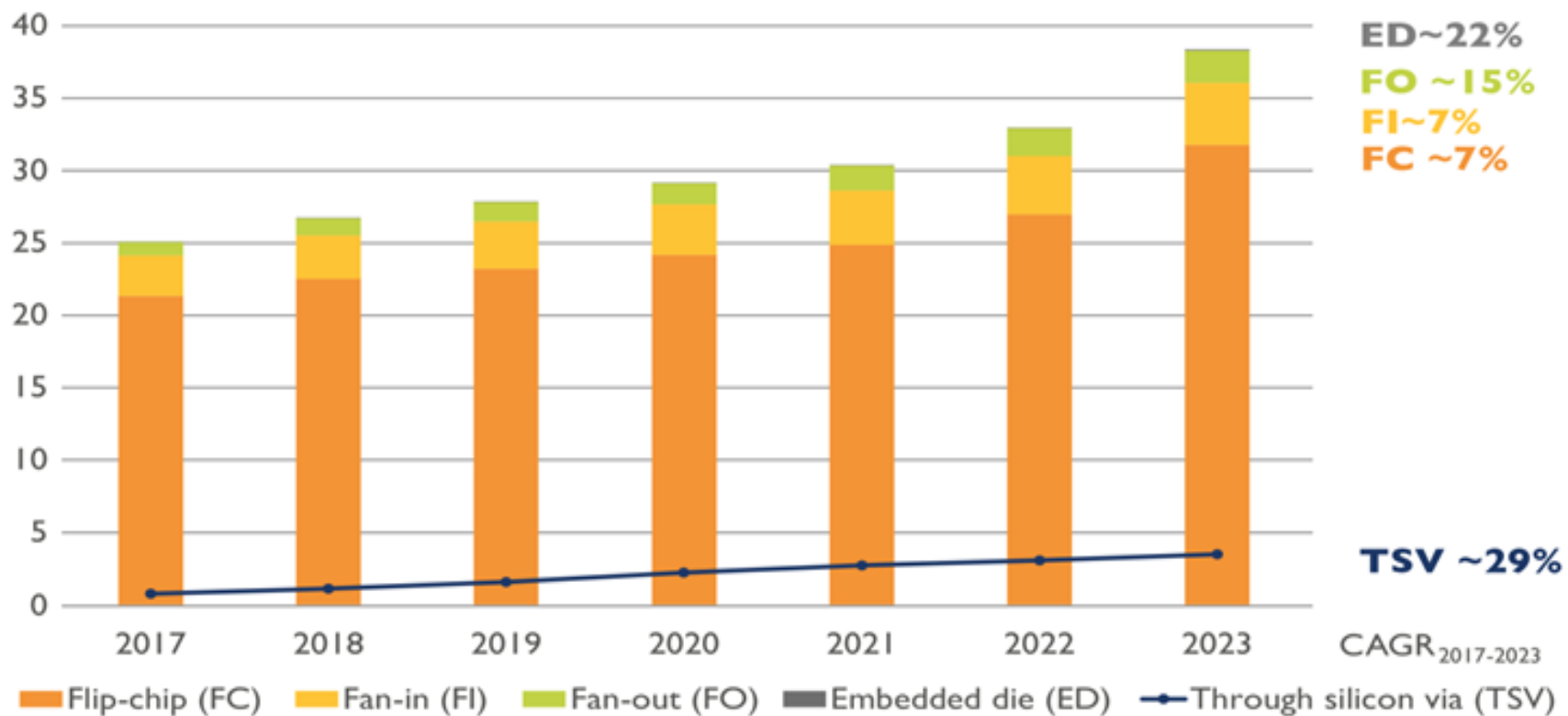




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# Industry Overview

## 2017 - 2023 advanced packaging revenue forecast, by packaging platform in \$B

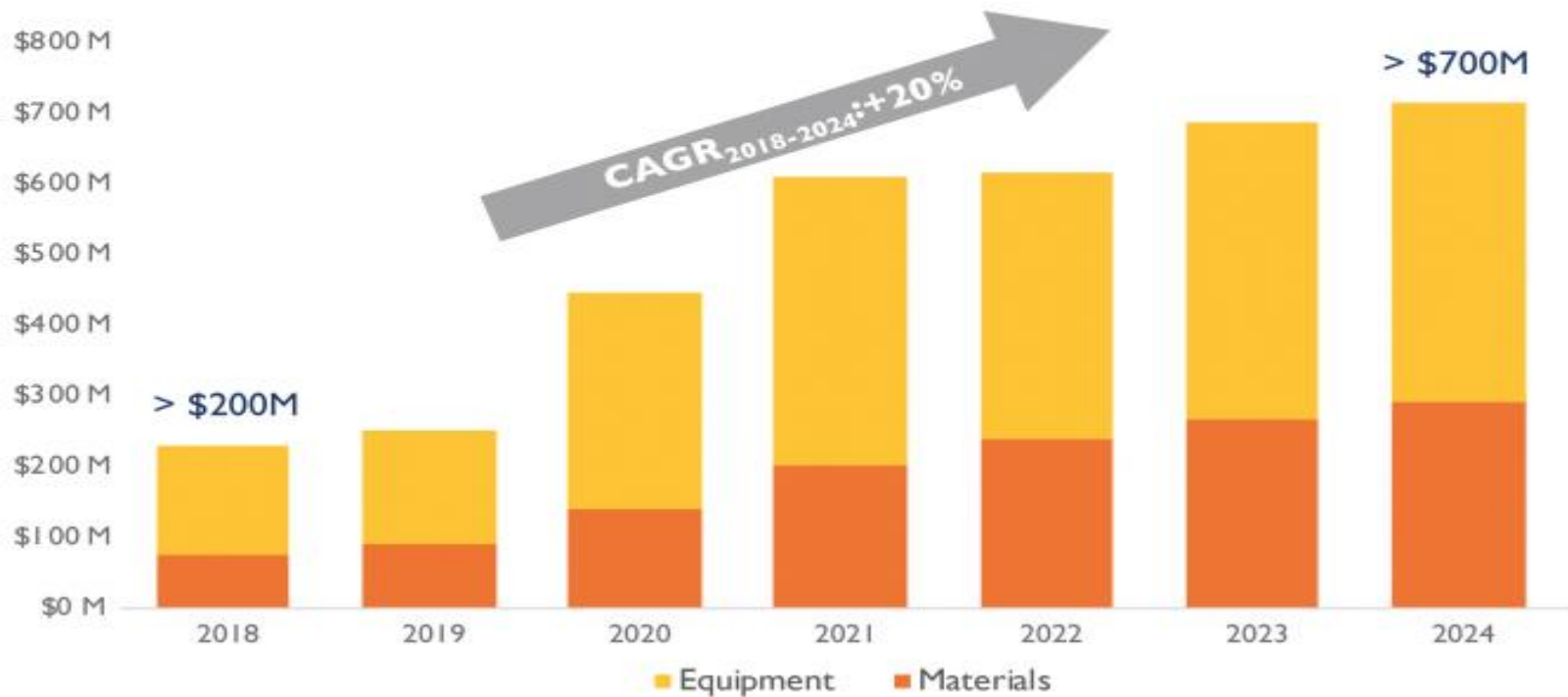


出處: (Source: Status of the Advanced Packaging Industry 2018 report, Yole Développement, September 2018)



# Industry Overview

## Equipment and materials in Fan-Out packaging revenue forecast

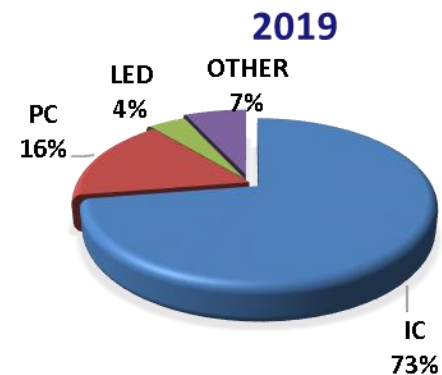
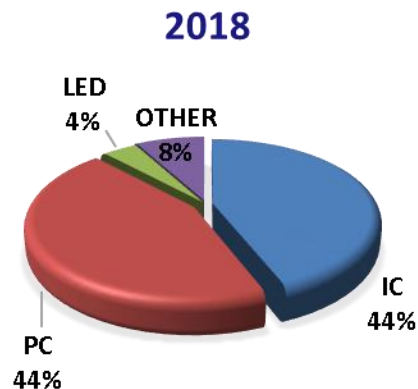
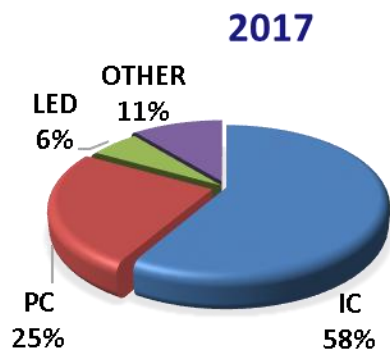


出處: (Source: Equipment and Materials for Fan-Out Packaging 2019 report, Yole Développement, 2019)



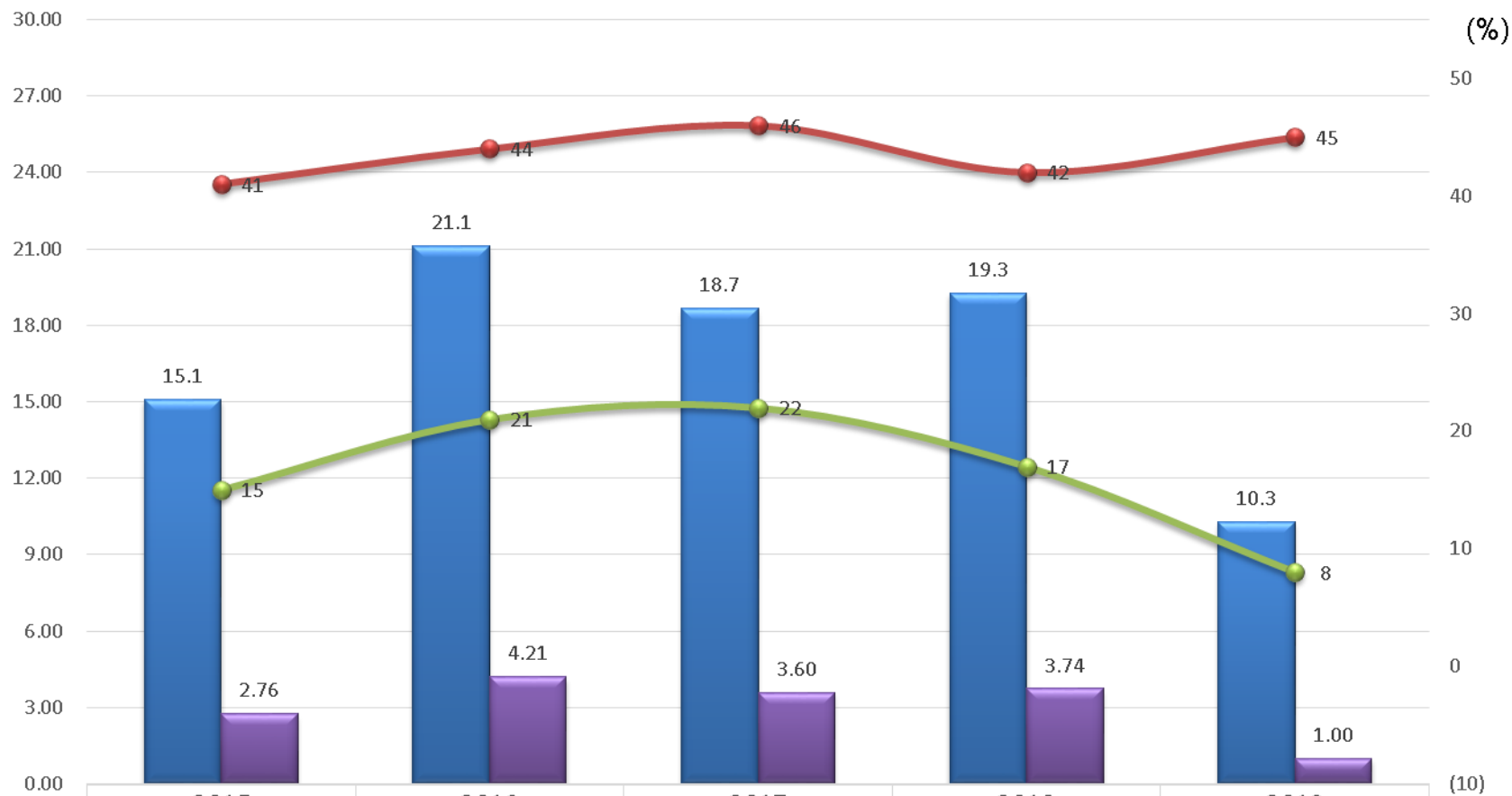
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# Revenue Breakdown



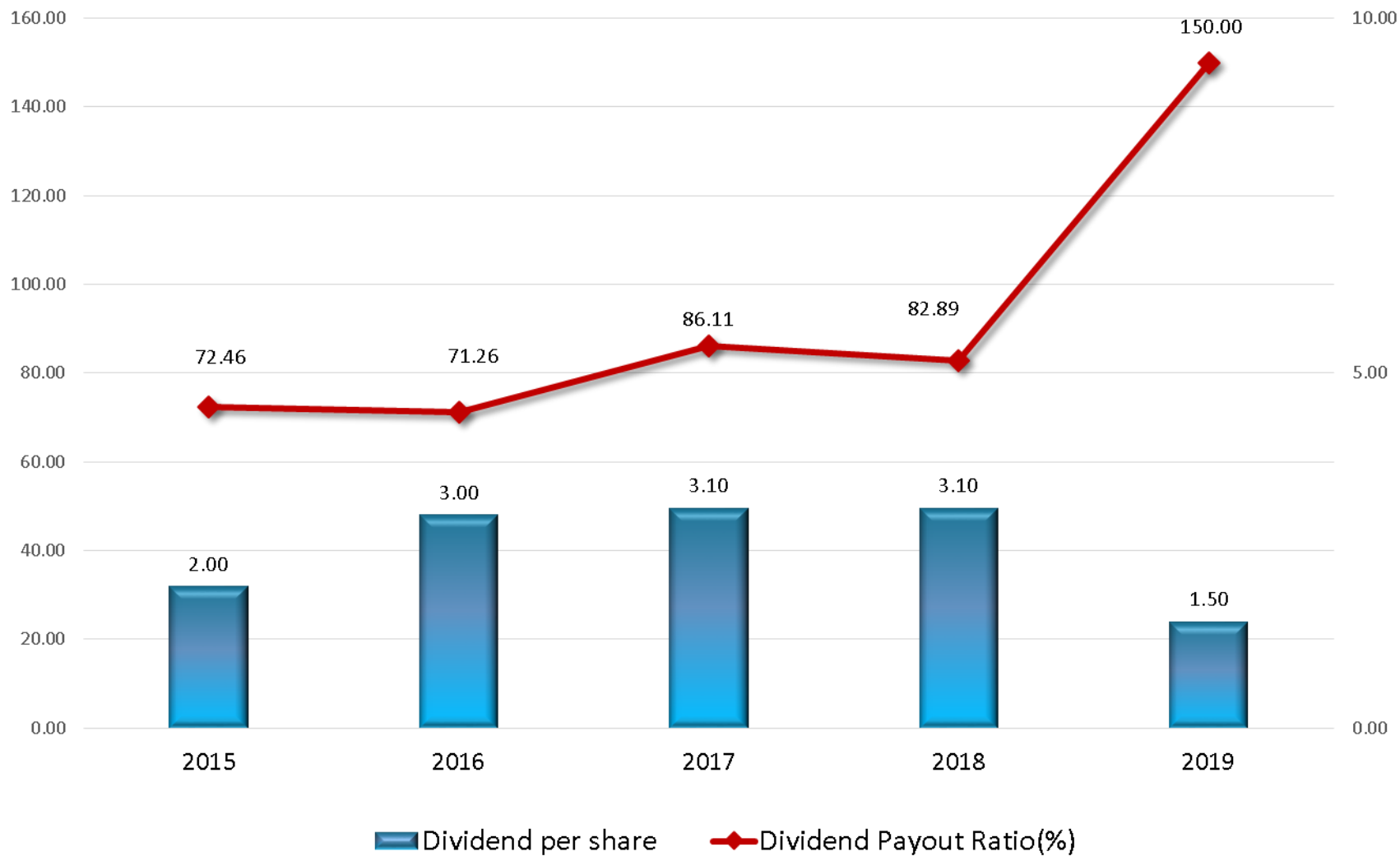
|              | 2017         | 2018         | 2019         |
|--------------|--------------|--------------|--------------|
| IC           | 10.89        | 8.46         | 7.48         |
| PC           | 4.64         | 8.49         | 1.7          |
| LED          | 1.11         | 0.77         | 0.43         |
| OTHER        | 2.03         | 1.54         | 0.71         |
| <b>TOTAL</b> | <b>18.67</b> | <b>19.26</b> | <b>10.32</b> |

# Financial Highlights



|             |      |      |      |      |      |
|-------------|------|------|------|------|------|
| Sales(NT億元) | 15.1 | 21.1 | 18.7 | 19.3 | 10.3 |
| EPS(NT\$)   | 2.76 | 4.21 | 3.60 | 3.74 | 1.00 |
| GM(%)       | 41   | 44   | 46   | 42   | 45   |
| OPM(%)      | 15   | 21   | 22   | 17   | 8    |

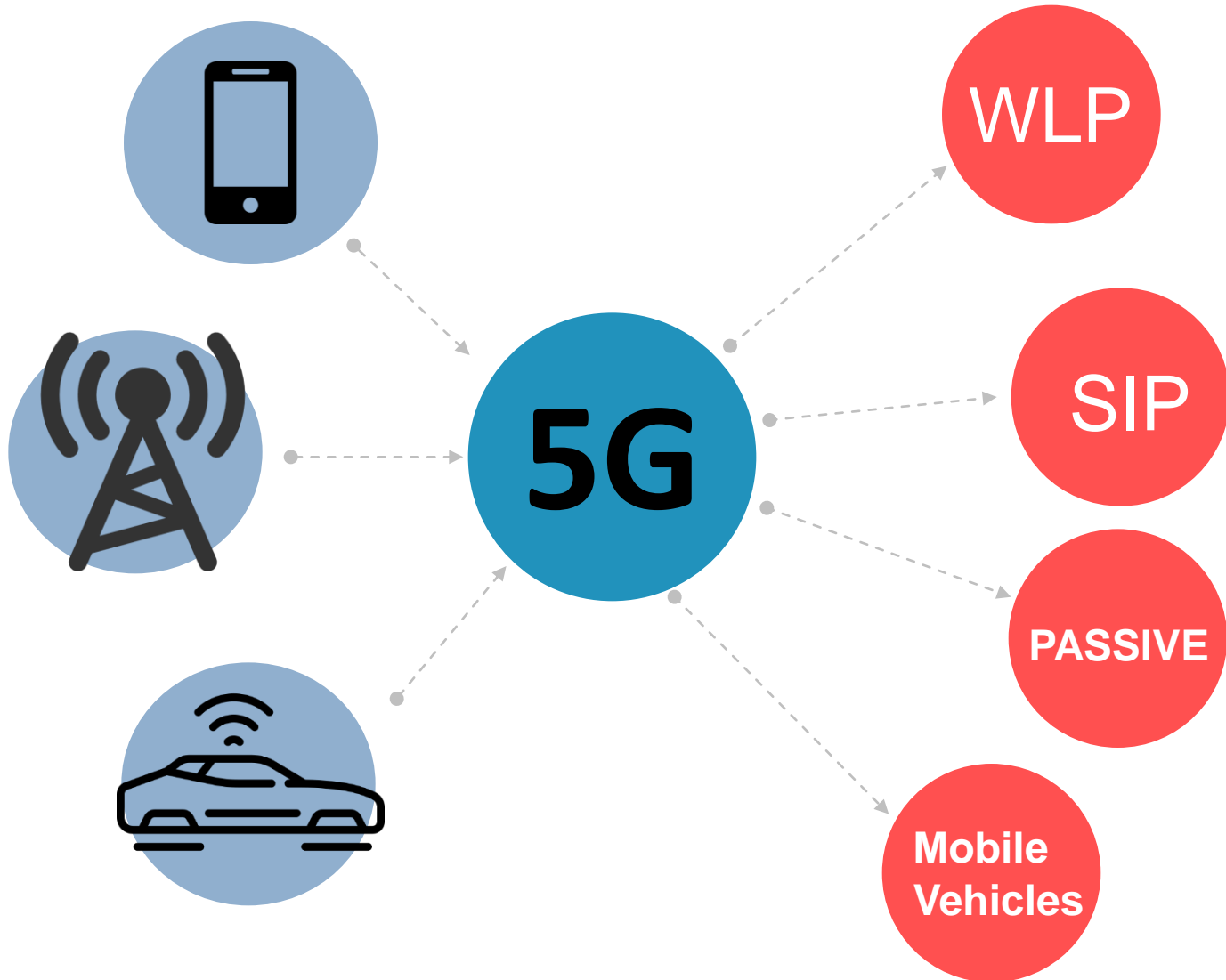
# Financial Highlights





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# Future Prospects





# Q & A



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